

EAST-10706210 stackable chip with feed-through.wsp:1

FileViewEditToolsWindowHelp

BRS: knall

BRS: 18 21 23

BRS: 32with 33

Pending

Active

L1: (22) (((carrier near 9 cavity) with ((open \$5 via hole aperture perforat \$4) 0

L2: (458238) (@ad @pd) > "20040425"

L3: (138) lip near 4 (portion section) near 4 bottom adj surface

L4: (30841) frustoconical

L5: (14) 3 and 4

L6: (4) 3 same 4

Failed

Saved

(1) 09/948877

(1738) "KONINKLIJKE PHILIPS".as.

(3) 09/344278

(8924363) (open \$5 via hole aperture perforat \$4)

(408215) (mcm: (multi adj chip adj module)) :stack \$4 near 2 (package chip module) (

(682754) cavity

(6829277) (open \$5 via hole aperture perforat \$4)

(408517) (mcm: (multi adj chip adj module)) :stack \$4 near 2 (package chip module) (

(683188) cavity

(30232) frustoconical

(30534) frustocon \$5

(83681) frustocon \$5 frusto adj conic \$2

(1134474) carrier

BrowseQueueClear

DBs:USPAT:US PGPUB: EPO: JPO: DERWENT: IBM: TDB

Default operator:GR

Plurals

+highlight all hit terms initially

3 same 4

Aug 2007

All newAll itemGroupFilter

#	Source	Document	Issue	P	Title	Current	Current X	Retrieval	S	C	P	Image	Doc	P
1	Moden, Walt	US 2001004	20011	1	Stackable ceramic fbga for high thermal appl	257/888	257/E23.00		F	F	F	F	US 200100	
2	Moden, Walt	US 6650007	20031	1	Stackable ceramic fbga for high thermal appl	257/686	257/685		F	F	F	F	US 665000	
3	Moden, Walt	US 6297548	20011	1	Stackable ceramic FBGA for high thermal ap	257/888	257/887		F	F	F	F	US 629754	
4	Moden, Walt	US 2004010	20040	1	Stackable ceramic FBGA for high thermal ap	257/200			F	F	F	F	US 200401	

Ready

3/2/04